

UTC UNISONIC TECHNOLOGIES CO., LTD

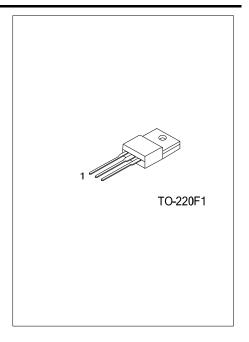
7N90 **Preliminary Power MOSFET**

7A, 900V N-CHANNEL POWER MOSFET

DESCRIPTION

The UTC 7N90 is an N-channel mode power MOSFET using UTC's advanced technology to provide costumers with planar stripe and DMOS technology. This technology specializes in allowing a minimum on-state resistance and superior switching performance. It also can withstand high energy pulse in the avalanche and commutation mode.

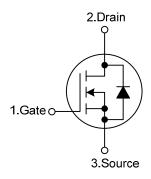
The UTC 7N90 is universally applied in active power factor correction, electronic lamp ballast based on half bridge topology and high efficient switched mode power supply.



FEATURES

- * High switching speed
- * $R_{DS(ON)}$ =1.8 Ω @ V_{GS} =10V
- * Typically 40nC low gate charge
- * 100% avalanche tested
- * Typically 17pF low C_{RSS}
- * Improved dv/dt capability

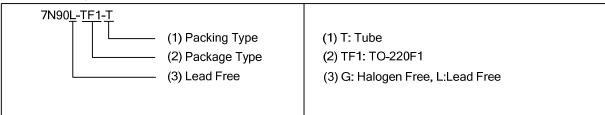
SYMBOL



ORDERING INFORMATION

	Ordering Number		Daalaaaa	Pin Assignment			Dankinn
Γ	Lead Free	Halogen Free	Package	1	2	3	Packing
Γ	7N90L-TF1-T	7N90G-TF1-T	TO-220F1	G	D	S	Tube

Note: Pin Assignment: G: Gate D: Drain S: Source



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■ ABSOLUTE MAXIMUM RATINGS

PARAMETER		SYMBOL	RATINGS	UNIT
Drain to Source Voltage		V _{DSS}	900	V
Gate to Source Voltage		V _{GSS}	±30	V
Continuous Drain Current	T _C =25°C	- I _D	7.0	Α
Continuous Drain Current	T _C =100°C		4.4	Α
Pulsed Drain Current (Note 2)		I _{DM}	28	Α
Avalanche Current (Note 2)		I _{AR}	6.4	Α
Single Pulsed Avalanche Energy (Note 3)		E _{AS}	500	mJ
Repetitive Avalanche Energy	(Note 2)	E _{AR}	21	mJ
Peak Diode Recovery dv/dt (Note 4)		dv/dt	4.0	V/ns
Power Dissipation		P _D	32	W
Junction Temperature		T_J	+150	°C
Storage Temperature		T _{STG}	-55 ~ +150	°C

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

- 2. Repetitive Rating: Pulse width limited by maximum junction temperature
- 3. L=20mH, I_{AS} =7.0A, V_{DD} = 50V, R_{G} =25 Ω , Starting T_{J} =25 $^{\circ}$ C
- 4. I_{SD} ≤7.0A, di/dt ≤200A/µs, V_{DD} ≤BV_{DSS}, Starting T_J=25°C

■ THERMAL DATA

PARAMETER	SYMBOL	RATINGS	UNIT	
Junction to Ambient	θ _{JA} 62.5		°C/W	
Junction to Case	θ _{JC}	3.87	°C/W	

■ **ELECTRICAL CHARACTERISTICS** (T_C=25°C, unless otherwise specified)

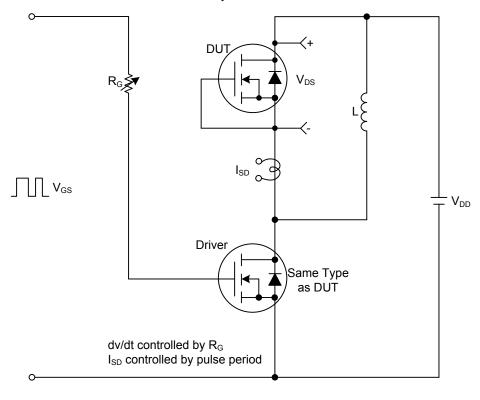
PARAMETER		SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
OFF CHARACTERISTICS								
Drain-Source Breakdown Voltage		BV _{DSS}	V _{GS} =0V, I _D =250μA	900			V	
Breakdown Voltage Temperature Coefficient		$\Delta BV_{DSS}/\Delta T_{J}$	I _D =250μA,Referenced to 25°C		0.96		V/°C	
Drain-Source Leakage Current		I _{DSS}	V _{DS} =900V, V _{GS} =0V			10	μΑ	
			V _{DS} =720V, T _C =125°C			100	μΑ	
Cata Sauraa Laakaga Current	Forward	I _{GSS}	V _{DS} =0V ,V _{GS} =30V			100	nΑ	
Gate-Source Leakage Current	Reverse	I _{GSS}	V _{DS} =0V ,V _{GS} =-30V			-100	nΑ	
ON CHARACTERISTICS						_		
Gate Threshold Voltage		$V_{GS(TH)}$	$V_{DS}=V_{GS}$, $I_D=250\mu A$	3.0		5.0	V	
Drain-Source On-State Resistan	ce	R _{DS(ON)}	V_{GS} =10V, I_D =3.5A		1.5	1.8	Ω	
Forward Transconductance		g FS	V _{DS} =50V, I _D =3.5A (Note 4)		5.7		S	
DYNAMIC PARAMETERS								
Input Capacitance		C _{ISS}			1440	1880	pF	
Output Capacitance		Coss	V _{DS} =25V,V _{GS} =0V,f=1.0MHz		140	185	pF	
Reverse Transfer Capacitance		C _{RSS}			17	23	pF	
SWITCHING PARAMETERS								
otal Gate Charge		Q_{G}	\/ -720\/ \/ -10\/		40	52	nC	
Gate-Source Charge		Q_GS	V _{DS} =720V, V _{GS} =10V, I _D =7.0A (Note 4,5)		8.5		nC	
Gate-Drain Charge		Q_GD	ID-7.0A (Note 4,5)		20		nC	
Turn-ON Delay Time		t _{D(ON)}			35	80	ns	
Turn-ON Rise Time		t_R	V _{DD} =450V, I _D =7.0A,		80	170	ns	
Turn-OFF Delay Time		t _{D(OFF)}	R _G =25Ω (Note 4.,5)		95	200	ns	
Turn-OFF Fall Time	urn-OFF Fall Time				55	120	ns	
SOURCE- DRAIN DIODE RATIN	NGS AND CI	HARACTERI	STICS		-	-		
Maximum Body-Diode Continuou	us Current	Is				6.4	Α	
Maximum Body-Diode Pulsed Cu	aximum Body-Diode Pulsed Current					25.6	Α	
Drain-Source Diode Forward Vol	n-Source Diode Forward Voltage		I _S =7.0A, V _{GS} =0V			1.4	V	
Body Diode Reverse Recovery Time		t _{rr}	V _{GS} =0V, I _S =7.0A,		400		ns	
Body Diode Reverse Recovery Charge		Q_{RR}	dI _F /dt=100A/μs (Note 4)		4.3		μC	

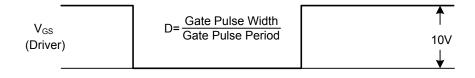
Notes: 1. Pulse Test : Pulse width \leq 300 μ s, Duty cycle \leq 2%

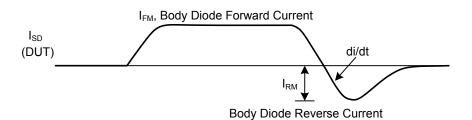
^{2.} Essentially independent of operating temperature

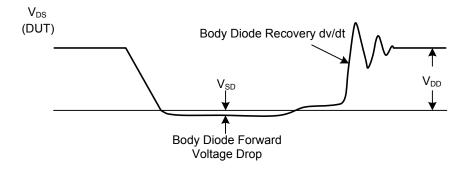
TEST CIRCUITS AND WAVEFORMS

Peak Diode Recovery dv/dt Test Circuit & Waveforms

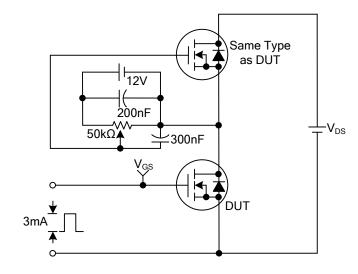




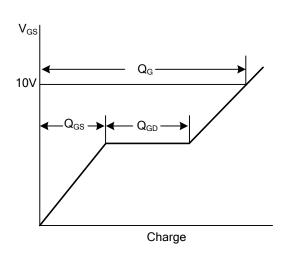




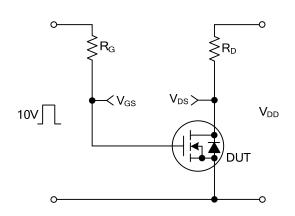
■ TEST CIRCUITS AND WAVEFORMS(Cont.)



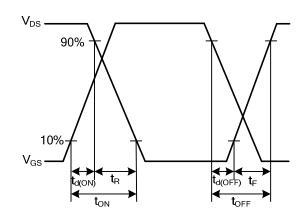
Gate Charge Test Circuit



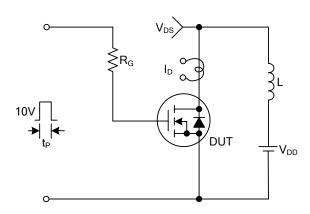
Gate Charge Waveforms



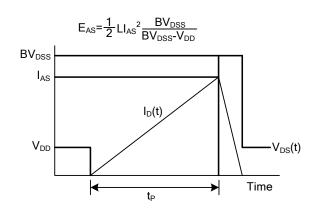
Resistive Switching Test Circuit



Resistive Switching Waveforms



Unclamped Inductive Switching Test Circuit



Unclamped Inductive Switching Waveforms

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